



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-04-17
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	KKK7*U367BHZ	A	SH1A	2014-04-17
Amount	UoM	Unit type	ST ECOPACK Grade	
130.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	kel/Palladium/Gold/Silver (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	8.6X3.9X1.52	12	gull wing	
Comment	Package: SO 14 .15 TO JEDEC MS-012 ; MD valid also for L6386ED			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	KKK7*U367BHZ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	3.582	mg	supplier	die	Silicon (Si)	7440-21-3		3.52	mg	982691	27077
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	1396	38
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.023	mg	6421	177
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.031	mg	8654	238
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	279	8
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.002	mg	558	15
Leadframe	Copper & its alloys	34.977	mg	supplier	alloy	Copper (Cu)	7440-50-8		34.868	mg	996884	268215
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.016	mg	457	123
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.029	mg	829	223
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.058	mg	1658	446
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.002	mg	57	15
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.002	mg	57	15
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.002	mg	57	15
Die attach	Other Organic Materials	0.717	mg	supplier	glue	Silver (Ag)	7440-22-4		0.359	mg	500697	2762
Die attach				supplier	glue	Aluminium (Al)	Proprietary		0.251	mg	350070	1931
Die attach				supplier	glue	acrylic resin	Proprietary		0.036	mg	50209	277
Die attach				supplier	glue	Ethylene glycol dicyclopentenyl ether acrylate	65983-31-5		0.057	mg	79498	438
Die attach				supplier	glue	[3-(2,3-epoxypropoxy)propyl] trimethoxysilan	2530-83-8		0.007	mg	9763	54
Die attach				supplier	glue	Butadiene copolymer	68891-50-9		0.007	mg	9763	54
Bonding wire	Other inorganic materials	0.066	mg	supplier	wire	Copper (Cu)	7440-50-8		0.066	mg	1000000	508
encapsulation	Other Organic Materials	90.658	mg	supplier	mold compound	Silica, vitreous	60676-86-0		79.507	mg	876999	611592
encapsulation				supplier	mold compound	Epoxy resin A	EC 413-900-7		3.626	mg	39996	27892
encapsulation				supplier	mold compound	Epoxy resin B	29690-82-2		3.626	mg	39996	27892
encapsulation				supplier	mold compound	phenol resin	Proprietary		2.72	mg	30003	20923
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.272	mg	3000	2092
encapsulation				supplier	mold compound	additive	Proprietary		0.907	mg	10005	6977